L Number	Hits	Search Text	DB	Time stamp
1	665	(welding welded) near3 metallurgical\$2	USPAT;	2004/03/17 09:32
			US-PGPUB; EPO; JPO; DERWENT	
2	44	((welding welded) near3 metallurgical\$2) and semiconductor and (chip die) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 09:32
3	2	5627406.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 08:06
4	1	5627406.pn. and (welding welded)	USPAT; US-PGPUB; EPO; JPO;	2004/03/17 08:07
5	2	5627406.pn. and metallurgical\$2	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/03/17 08:08
6	35	(pressure nearl (welding welded)) with metallurgical\$2	DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 10:38
7	128	(welding welded) with metallurgical\$2 with pressure	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 09:32
9	0	<pre>(((welding welded) with metallurgical\$2 with pressure) and (semiconductor chip die) and (bump ball)) not ((welding welded) near3 metallurgical\$2) and semiconductor and (chip die) and (bump ball))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 09:33
8	33		USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 09:36
10	35	((welding welded) with metallurgical\$2 with pressure) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 09:37
11	2	<pre>(((welding welded) with metallurgical\$2 with pressure) and (bump ball)) not (((welding welded) with metallurgical\$2 with pressure) and (semiconductor chip die) and (bump ball))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 09:37
12	0	jp407130749a	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 10:32
13	0	jp47130749a	USPAT; US-PGPUB; EPO; JPO;	2004/03/17 10:34
14	0	jp40292773a .	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/03/17 10:33
15	0	jp400292773a	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/03/17 10:33
16	0	jp470130749a	DERWENT USPAT; US-PGPUB; EPO; JPO;	2004/03/17 10:34
17	0	jp47130749	DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/17 10:34

18	0	jp407130749a	USPAT;	2004/03/17 10:43
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
19	0	jp307130749a	USPAT;	2004/03/17 10:36
			US-PGPUB;	
			EPO; JPO;	
	_		DERWENT	
20	0	(pressure nearl (welding welded)) and ball	JPO	2004/03/17 10:39
1	_	and metallurgical\$2		
21	1	(pressure nearl (welding welded)) and ball	JPO;	2004/03/17 10:39
	0.0	and metallurgical\$2	DERWENT	
22	28	(pressure nearl (welding welded)) and	JPO;	2004/03/17 10:39
	1.0	metallurgical\$2	DERWENT	
23	13	(pressure near1 (welding welded)) and	JPO	2004/03/17 10:39
	0	metallurgical\$2	HCDAM.	2004/02/17 10:44
24	"	JP407130749A	USPAT;	2004/03/17 10:44
			US-PGPUB;	
			EPO; JPO; DERWENT	
			DEVMENT	

L Number	Hits	Search Text	DB	Time stamp
1	0	(metallurgical\$2 near1 (bonding bond	JPO	2004/03/17 14:03
		bonded)) near3 (bump ball)		
2	80	(metallurgical\$2 near1 (bonding bond	USPAT;	2004/03/17 14:03
		bonded)) near3 (bump ball)	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
3	67	' ' 3	USPAT;	2004/03/17 14:04
		bonded)) near3 (bump ball)) and	US-PGPUB;	
		semiconductor and (chip die)	EPO; JPO;	
			DERWENT	
4	4	((metallurgical\$2 near1 (bonding bond	USPAT;	2004/03/17 14:07
		bonded)) near3 (bump ball)) with	US-PGPUB;	
		semiconductor and (chip die)	EPO; JPO;	
			DERWENT	
5	19	((metallurgical\$2 near1 (bonding bond	USPAT;	2004/03/17 14:07
		bonded)) near3 (bump ball)) with	US-PGPUB;	
		(semiconductor chip die)	EPO; JPO;	
	<u></u>		DERWENT	